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U.S. DEPARTMENT OF COMMERCE
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Form PTO-105

08-11-2001

OMB No. 0651-0027 (Exp. 5/31/2002)

Tab settings

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Zeevo, Inc.

8-13-01

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:



Assignment



Merger



Security Agreement



Change of Name



Other

Execution Date: July 2, 2001

2. Name and address of receiving party(ies)

Name: GATX Ventures, Inc.

Internal Address: ATTN: Legal

Street Address: 3687 Mt. Diablo Blvd.,

Suite 200

City: Lafayette State: CA Zip: 94549

Additional name(s) & address(es) attached? ☒ Yes ☐ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

See attached.

B. Patent No.(s)

Additional numbers attached? ☒ Yes ☐ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: GATX Ventures, Inc.

Internal Address: ATTN: Legal

Street Address: 3687 Mt. Diablo Blvd.,

Suite 200

City: Lafayette State: CA Zip: 94549

6. Total number of applications and patents involved: 10

7. Total fee (37 CFR 3.41).....\$



Enclosed



Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Maureen C. Dellinger, In-House
Counsel for GATX Ventures, Inc.

Name of Person Signing

Maureen C. Dellinger

Signature

August 9, 2001

Date

Total number of pages including cover sheet, attachments, and documents: 7

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

08/16/2001 ANNED1 00000076 09553734

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PATENT
REEL: 012070 FRAME: 0007

2. Additional name and address of receiving part(ies)

Transamerica Commercial Finance Corporation
76 Batterson Park Road
Farmington, CT 06032

With a copy to:

Transamerica Commercial Finance Corporation
9399 West Higgins Road, Suite 600
Rosemont, Illinois 60018

SCHEDULE 1-A TO GRANT OF SECURITY INTEREST

PATENTS

None

SCHEDULE 1-B TO GRANT OF SECURITY INTEREST

PATENT APPLICATIONS

Patent Application	Application Date	Application Number
RF Receiver with Enhanced IF, Direct Frequency Conversion	4/20/2000	09/553734
Method for Designing Mixed Signal Integrated Circuits And Configurable Synchronous Digital Noise Emulator Circuit	7/19/2000	09/618971
Automatic Gain Control Circuit for Signal with Diverse Power Level Range	8/24/2000	09/645475
DC Offset Correction Technique, Applicable for use in an Enhanced Direct Conversion Radio Architecture	3/20/2001	09/813420
An image-reject mixer with means of DC offset calibration (called, DC Offset Calibration for a Radio Transceiver Mixer)	5/15/2001	09/858812
A new structure and process for increasing MIM cap density	4/26/2001	09/844293
Method for Linear Combining (officially submitted as, CMOS Frequency Conversion Using Dual Mixers for Sideband Suppression)	4/2/2001	09/825250
AC Coupled CMOS Inverter Buffered Amplifiers (called, Efficient AC Coupled CMOS RF Amplifier)	4/2/2001	09/825252

Enhanced CMOS Logarithmic IF amplifier with dynamic large signal bias circuit (also called, Logarithmic IF Amplifier With Dynamic Large Signal Bias Circuit)	4/16/2001	09/836624
Low Power Large Signal RF Tuned Buffer Amplifier	4/13/2001	09/835021
A variable transconductance design that can be used in System On Chip type applications (also called, Transconductance Device Employing Native MOS transistors)	4/18/2001	09/837897
A crystal oscillator circuit topology for reliable start-up within a System On a Chip architecture (SOC) - (also called, Oscillator Circuit with Signal Buffering and Start-up Circuitry)	4/10/2001	09/832686
Seal Ring Structure for IC Containing Integrated Digital/RF/Analog Circuits & Functions	4/30/2001	09/846335
Area Efficient Bond Pad Placement	5/2/2001	09/847948
Reduced Instruction Set Baseband Controller	3/23/2001	60/278493
System for Maintaining Synchronization Between Multiple Asynchronous Communication Links	3/21/2001	60/278362

4.A. Application number(s) and patent number(s) continued:**PATENT APPLICATIONS**

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System for Maintaining Synchronization Between Multiple Asynchronous Communication Links	3/21/2001	60/278362

GRANT OF SECURITY INTEREST

PATENTS

THIS GRANT OF SECURITY INTEREST, dated as of July 2, 2001, is executed by ZEEVO, INC., a Delaware corporation ("Debtor"), in favor of GATX VENTURES, INC. and TRANSAMERICA COMMERCIAL FINANCE CORPORATION (together, the "Secured Parties").

A. Pursuant to a Loan and Security Agreement dated as of July 2, 2001 (the "Agreement") among Debtor and the Secured Parties, the Secured Parties have agreed to extend certain credit facilities to Debtor upon the terms and subject to the conditions set forth therein;

B. Debtor owns the letters patent and/or applications for letters patent, of the United States, more particularly described on Schedules 1-A and 1-B annexed hereto as part hereof (collectively, the "Patents");

C. Pursuant to the Agreement, Debtor has granted to Secured Parties a security interest in all right, title and interest of Debtor in and to the Patents, together with any reissue, continuation, continuation-in-part or extension thereof, and all proceeds thereof, including any and all causes of action which may exist by reason of infringement thereof for the full term of the Patents (the "Collateral"), to secure the prompt payment, performance and observance of the Obligations, as defined in the Agreement;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, Debtor does hereby further grant to Secured Parties a security interest in the Collateral to secure the prompt payment, performance and observance of the Obligations.

Debtor does hereby further acknowledge and affirm that the rights and remedies of Secured Parties with respect to the security interest in the Collateral granted hereby are more fully set forth in the Agreement, the terms and provisions of which are hereby incorporated herein by reference as if fully set forth herein.

Secured Parties' addresses are: GATX Ventures, Inc.
3687 Mount Diablo Blvd., Suite 200
Lafayette, California 94549

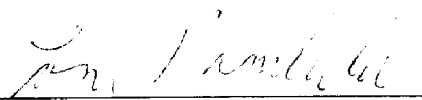
Transamerica Commercial Finance Corporation
76 Batterson Park Road
Farmington, CT 06032

With a copy to:

Transamerica Commercial Finance Corporation
9399 West Higgins Road, Suite 600
Rosemont, Illinois 60018

IN WITNESS WHEREOF, Debtor has caused this instrument to be executed as of the day and year first written above.

ZEEVO, INC.

By: 
Name: Louis Padolza
Title: VP Engineering